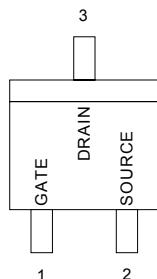


GENERAL DESCRIPTION

This N-Channel enhancement mode field effect transistor is produced using high cell density, DMOS technology. These products have been designed to minimize on-state resistance while providing rugged, reliable, and fast switching performance. It can be used in most applications requiring up to 115mA DC and can deliver pulsed currents up to 800mA. This product is particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

PIN CONFIGURATION

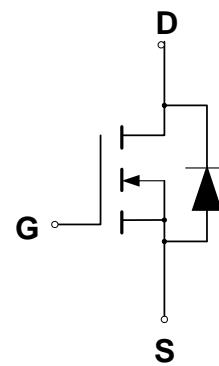
SOT-23
Top View



FEATURES

- ◆ High Density Cell Design for Low $R_{DS(ON)}$
- ◆ Voltage Controlled Small Signal Switch
- ◆ Rugged and Reliable
- ◆ High Saturation Current Capability

SYMBOL



N-Channel MOSFET

ORDERING INFORMATION

Part Number	Package
CMT2N7002	SOT-23
CMT2N7002G*	SOT-23

*Note: G : Suffix for Pb Free Product

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain Source Voltage	V_{DSS}	60	V
Drain-Gate Voltage ($R_{GS} = 1.0M\Omega$)	V_{DGR}	60	V
Drain to Current - Continuous - Pulsed	I_D I_{DM}	± 115 ± 800	mA
Gate-to-Source Voltage - Continue - Non-repetitive	V_{GS} V_{GSM}	± 20 ± 40	V
Total Power Dissipation Derate above 25	P_D	225 1.8	mW mW/
Single Pulse Drain-to-Source Avalanche Energy - $T_J = 25$ ($V_{DD} = 50V$, $V_{GS} = 10V$, $I_{AS} = 0.8A$, $L = 30mH$, $R_G = 25\Omega$)	E_{AS}	9.6	mJ
Operating and Storage Temperature Range	T_J , T_{STG}	-55 to 150	
Thermal Resistance - Junction to Ambient	θ_{JA}	417	/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	300	

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^\circ C$.

Characteristic		CMT2N7002				
		Symbol	Min	Typ	Max	Units
Drain-Source Breakdown Voltage ($V_{GS} = 0 V$, $I_D = 10 \mu A$)		$V_{(BR)DSS}$	60			V
Drain-Source Leakage Current ($V_{DS} = 60 V$, $V_{GS} = 0 V$) ($V_{DS} = 60 V$, $V_{GS} = 0 V$, $T_J = 125^\circ C$)		I_{DSS}			1.0 0.5	μA mA
Gate-Source Leakage Current-Forward ($V_{gsf} = 20 V$)		I_{GSSF}			100	nA
Gate-Source Leakage Current-Reverse ($V_{gsf} = -20 V$)		I_{GSSF}			-100	nA
Gate Threshold Voltage *		$V_{GS(th)}$	1.0		2.5	V
($V_{DS} = V_{GS}$, $I_D = 250 \mu A$)						
On-State Drain Current ($V_{DS} = 2.0 V_{DS(on)}$, $V_{GS} = 10V$)		$I_{d(on)}$	500			mA
Static Drain-Source On-Resistance *		$R_{DS(on)}$			7.5 13.5 7.5 13.5	Ω
($V_{GS} = 10 V$, $I_D = 0.5A$) ($V_{GS} = 10 V$, $I_D = 0.5A$, $T_C = 125^\circ C$) ($V_{GS} = 5.0 V$, $I_D = 50mA$) ($V_{GS} = 5.0 V$, $I_D = 50mA$, $T_C = 125^\circ C$)						
Drain-Source On-Voltage *		$V_{DS(on)}$			3.75 0.375	V
($V_{GS} = 10 V$, $I_D = 0.5A$) ($V_{GS} = 5.0 V$, $I_D = 50mA$)						
Forward Transconductance ($V_{DS} = 2.0 V_{DS(on)}$, $I_D = 200mA$) *		g_{FS}	80			mmhos
Input Capacitance	$(V_{DS} = 25 V$, $V_{GS} = 0 V$, $f = 1.0 \text{ MHz}$)	C_{iss}			50	pF
Output Capacitance		C_{oss}			25	pF
Reverse Transfer Capacitance		C_{rss}			5.0	pF
Turn-On Delay Time	$(V_{DD} = 25 V$, $I_D = 500 mA$, $V_{gen} = 10 V$, $R_G = 25\Omega$, $R_L = 50\Omega$) *	$t_{d(on)}$			20	ns
Turn-Off Delay Time		$t_{d(off)}$			40	ns
Diode Forward On-Voltage ($I_S = 115 mA$, $V_{GS} = 0V$)		V_{SD}			-1.5	V
Source Current Continuous (Body Diode)		I_S			-115	mA
Source Current Pulsed		I_{SM}			-800	mA

* Pulse Test: Pulse Width 300 μs , Duty Cycle 2%

TYPICAL ELECTRICAL CHARACTERISTICS

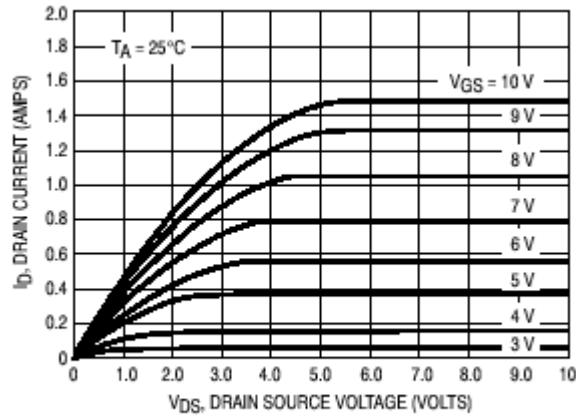


Figure 1. Ohmic Region

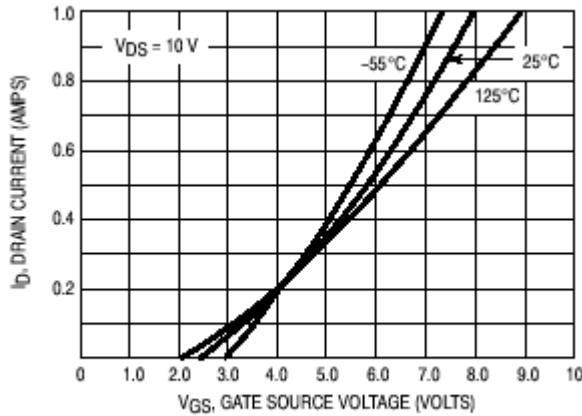


Figure 2. Transfer Characteristics

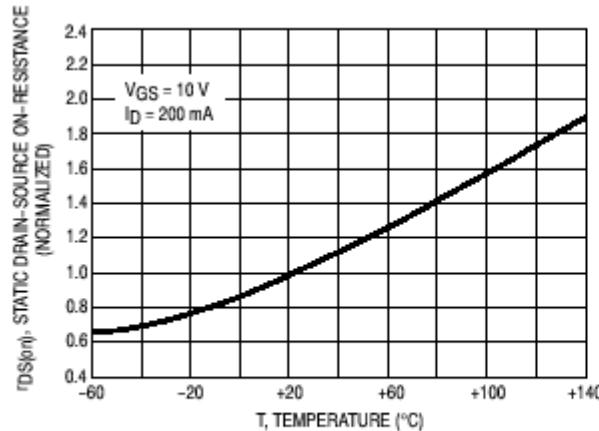


Figure 3. Temperature versus Static Drain-Source On-Resistance

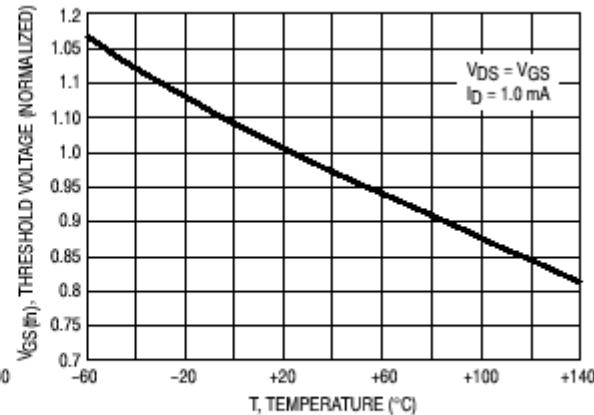
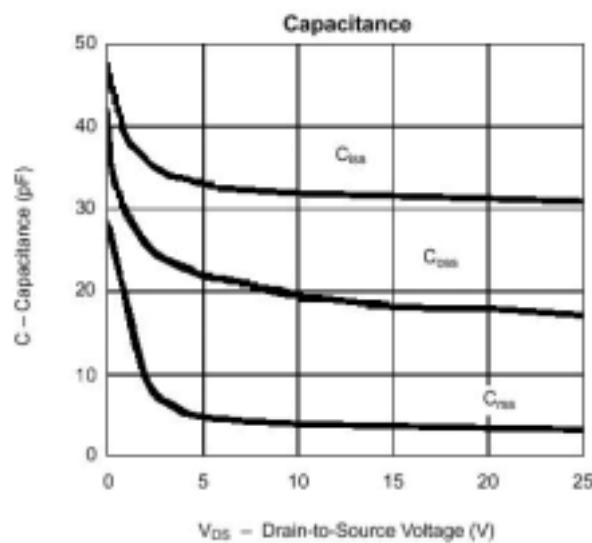


Figure 4. Temperature versus Gate Threshold Voltage



V_{DS} = Drain-to-Source Voltage (V)

Figure 5. Capacitance

PACKAGE DIMENSION

